

What is claimed is:

1. A socket or adapter device, comprising at least one connection pin, the connection pin configured to be introduced into a corresponding contact device of a device to which the socket or adapter device is to be connected, wherein
the connection pin is configured such that a clamping connection is provided between the contact device and the connection pin when the connection pin is introduced into the contact device.
2. The socket or adapter device according to claim 1, wherein the socket or adapter device is a semiconductor device testing socket or a semiconductor device testing adapter, respectively, which is configured such that, for testing a semiconductor device, it is loaded with a corresponding semiconductor device.
3. The socket or adapter device according to claim 1, wherein the socket or adapter device is a burn-in socket or a burn-in adapter, respectively, which is configured such that, for performing a burn-in test, it is loaded with a corresponding semiconductor device.
4. The socket or adapter device according to claim 1, wherein the connection pin is made of a flexible or resilient material.
5. The socket or adapter device according to claim 4, wherein the metal alloy includes copper and/or beryllium.

6. The socket or adapter device according to claim 1, wherein at least one section of the connection pin has a curved shape.

5 7. The socket or adapter device according to claim 6, wherein the section of the connection pin has the shape of a wave attenuated in a direction leading away from the socket or adapter device.

10 8. The socket or adapter device according to claim 1, wherein the device comprising the contact device is a circuit board configured to be connected to a testing apparatus.

15 9. The socket or adapter device according to claim 1, wherein the device comprising the contact device is a testing apparatus.

10. The socket or adapter device according to claim 1, wherein the contact device comprises a recess or a bore into which the connection pin is introduced.

11. A system, comprising:

at least one socket or adapter device; and

25 at least one semiconductor device testing apparatus or at least one circuit board, wherein

the socket or adapter device comprises at least one connection pin which is configured to be introduced into a corresponding contact device for connection to the testing apparatus or to the circuit board that can be
30 connected with a testing apparatus,

wherein the connection pin is configured such that a clamping connection is provided between the contact device and the connection pin when the connection pin is introduced into the contact device.

5

12. The system according to claim 11, wherein the connection between the connection pin and the contact device is performed without soldering.

10 13. The system according to claim 12, wherein the socket or adapter device comprises a plurality of connection pins that are connected with respectively corresponding contact devices, and wherein the connections between the connection pins and the respectively corresponding contact devices each are performed without soldering.

15

14. A method for testing semiconductor devices, comprising:

connecting a socket or adapter device to a testing
20 system, wherein at least one connection pin of the socket or adapter device is introduced into a corresponding contact device;

loading the socket or adapter device with a semiconductor device to be tested,

25 wherein the connection pin is configured such that a clamping connection is provided between the contact device and the connection pin when the connection pin is introduced into the contact device.

30